



ANSYS And TSMC Enable Chip Manufacturers To Create Cutting-Edge Electronic Products

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PITTSBURGH, March 15, 2016 /PRNewswire/ -- Manufacturers of advanced electronic products – ranging from mobile and networking appliances to futuristic Internet of Things devices – will become more powerful, smaller and more energy efficient thanks to new advances from [TSMC](#) and [ANSYS](#) (NASDAQ: ANSS).



TSMC's certification of ANSYS solutions for its 10nm FinFET process technology, enables customers to deliver their innovative and reliable products to market faster while minimizing design costs and risk. TSMC also certified ANSYS solutions for the latest 7nm design rule manual and SPICE model for early design starts. Additionally, ANSYS solutions are enabled for TSMC's Integrated Fanout (InFO), the advanced wafer-level packaging technology for three-dimensional integrated circuits.

Today's cutting-edge electronic products demand minimal power yet still be reliable under a variety of conditions while still being affordable. These requirements place demands on the chip as well as a package, board and system. The TSMC certification provides users with a proven design process for advanced System on a Chip (SoC) – making new and innovative devices more affordable for consumers.

ANSYS design solutions support TSMC's InFO technology to provide cost-effective scaling to increase system bandwidth, reduced power consumption and smaller form factors while shortening overall design turnaround time. Compared to other methodologies, InFO is an ideal solution for mobile and IoT applications.

TSMC's certification of ANSYS solutions for its advanced FinFET process technologies enables designers to address the power integrity and reliability requirements for any given chip. Customers will have the power to perform the most accurate static and dynamic voltage drop analysis and advanced signal and power electromigration verification. This empowers users to innovate the next generation of SoC designs for use in mobile, computing and networking applications.

"Certification of ANSYS solutions for TSMC's latest technology gives our mutual customers a competitive advantage when designing complex SoCs," said John Lee, general manager, ANSYS. "In addition, we're working with TSMC to expand our existing solution scope to support InFO technology, driving the delivery of advanced power integrity and reliability solutions across package, board and system levels, enabling customers to innovate at the chip-package-system levels."

"Our close collaboration with ANSYS has enabled the delivery of advanced power integrity solutions including the analysis of thermal effects in FinFET technologies," said Suk Lee, senior director, design infrastructure marketing division at TSMC. "The certification for 10nm and 7nm, and the enablement of multiple ANSYS solutions for TSMC's InFO packaging, ensures tool readiness for advanced FinFET technologies and allows customers to analyze and design power delivery networks for 3D-ICs with confidence."

About ANSYS, Inc.

ANSYS is the global leader in engineering simulation. We bring clarity and insight to our customer's most complex design challenges through the broadest portfolio of fast, accurate and reliable simulation tools. Our technology enables organizations in all industries to imagine high-quality, innovative and sustainable product designs that have an accelerated time to market. Founded in 1970, ANSYS employs almost 3000 professionals, more than 700 of them with PhDs in engineering fields such as finite element analysis, computational fluid dynamics, electronics and electromagnetics, embedded software, system simulation and design optimization. Headquartered south of Pittsburgh, U.S.A., ANSYS has more than 75 strategic sales and development locations throughout the world with a network of channel partners in 40+ countries. Visit www.ansys.com for more information.

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